

TITLE OF THE INVENTION: RESIN COMPOSITION, RESIN
COMPOSITION COATING FILM, RESIN COMPOSITION FILM, CURED
FILM, AND SEMICONDUCTOR DEVICE USING THESE PRODUCTS

ABSTRACT

Disclosed is a resin composition including at least one polymer compound selected from the group consisting of polyamide, polyimide, polyamideimide and polybenzoxazole as a component (A), a cationic polymerizable compound as a component (B), and a photocationic polymerization initiator as a component (C), wherein the component (B) contains both an epoxy compound as a component (B1) and an oxetane compound as a component (B2). The present invention provides a resin composition which has sufficient mechanical properties and thermal properties and is capable of forming a pattern with thick film and high aspect ratio.

[FIG. 2]

